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Siliup Semiconductor

2N7002KT7

60V N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
60V	1.1Ω@10V	340mA
	1.4Ω@4.5V	

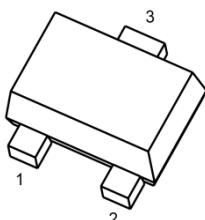
Feature

- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Capable doing Cu wire bonding
- ESD protected Gate HBM 2KV

Application

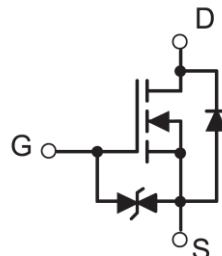
- Power Management in Note book
- Portable Equipment
- Battery Powered System

Package:

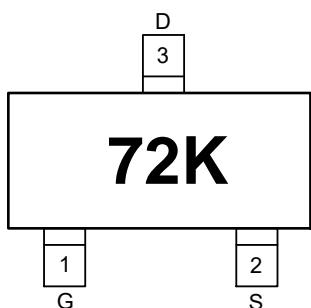


SOT-723

Circuit diagram



Marking



72K =Device Code



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Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	340	mA
Power Dissipation	P _D	0.15	W
Thermal Resistance from Junction to Ambient	R _{θJA}	833	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~ +150	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	60			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.5	2.5	V
Gate-Body Leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =200mA		1.1	3	Ω
		V _{GS} =4.5V, I _D =200mA		1.4	4	
Dynamic characteristics						
Total Gate Charge	Q _g	V _{DS} =10V, V _{GS} =4.5V, I _D =250mA		0.3		nC
Gate-Source Charge	Q _{gs}			0.2		
Gate-Drain Charge	Q _{gd}			0.08		
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1MHz		30	50	pF
Output Capacitance	C _{oss}			4.2	25	
Reverse Transfer Capacitance	C _{rss}			2.9	5	
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V, I _D =200mA, V _{GEN} =10V, R _G =25Ω		3.9		ns
Turn-On Rise Time	t _R			3.4		
Turn-Off Delay Time	t _{d(off)}			15.7		
Turn-Off Fall Time	t _F			9.9		
Source-Drain Diode characteristics						
Diode Forward Voltage	V _{SD}	I _S =200mA, V _{GS} =0V		0.82	1.3	V



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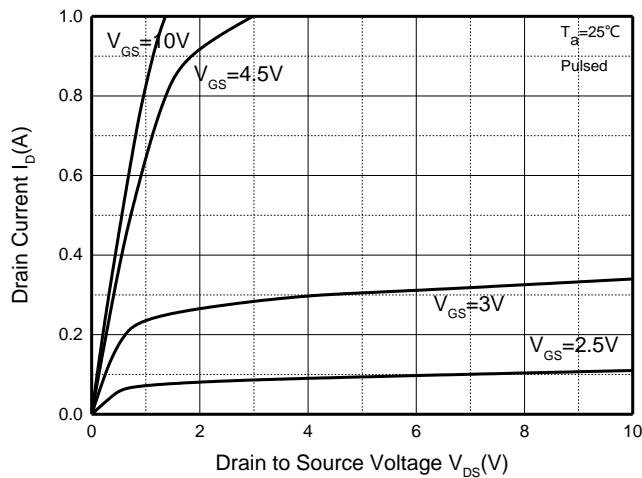
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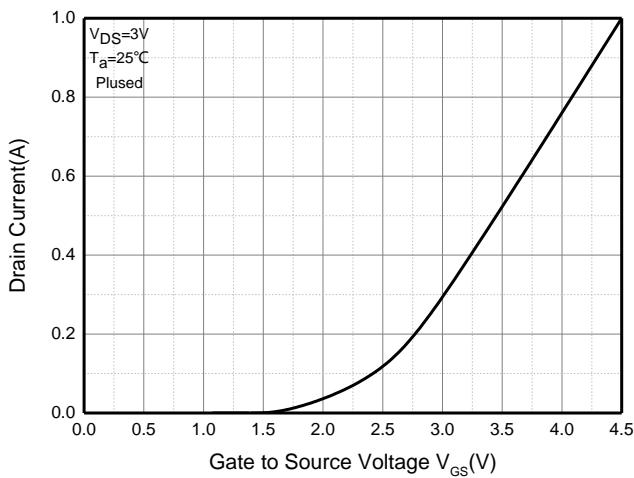
60V N-Channel MOSFET

Typical Characteristics

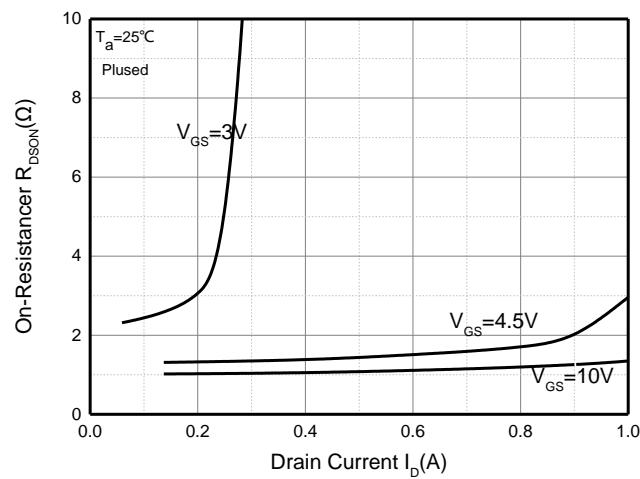
Output Characteristics



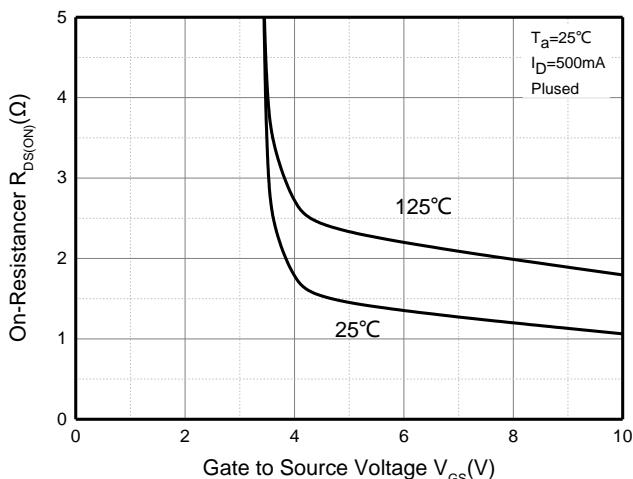
Transfer Characteristics



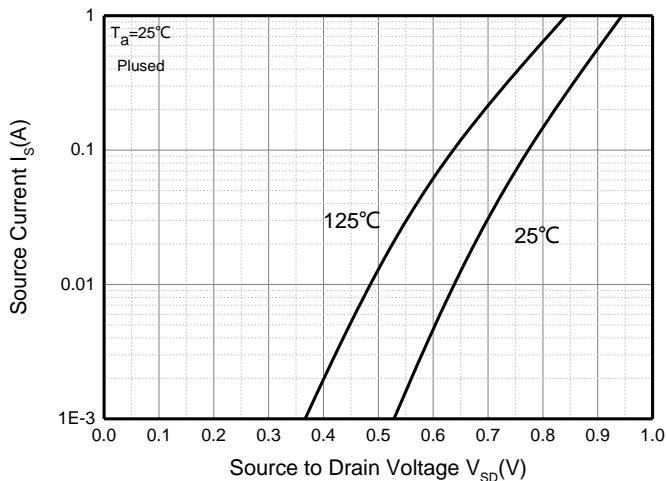
On-Resistance vs. Drain current



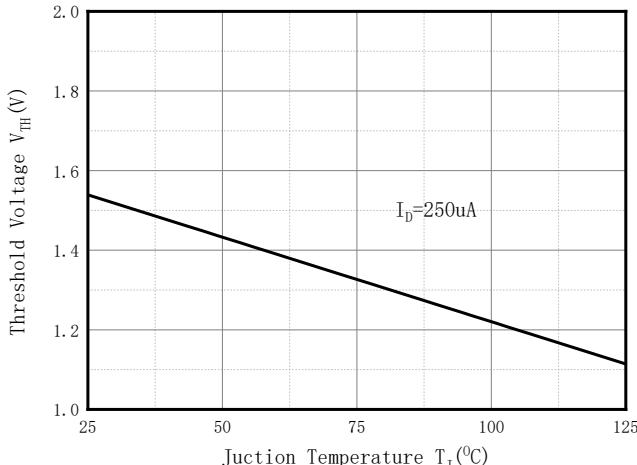
On-Resistance vs. Gate to Source Voltage



Source Current vs. Source to Drain Voltage



Threshold voltage vs. Junction temperature





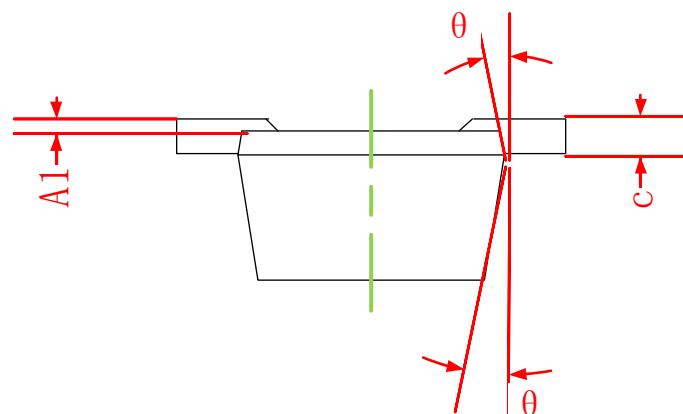
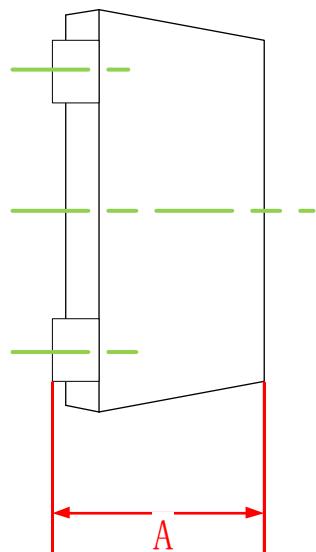
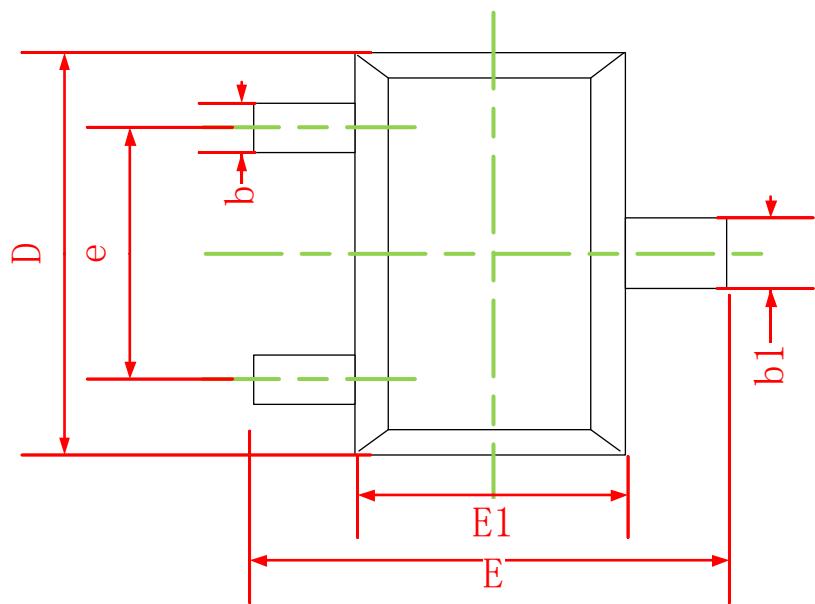
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SOT-723 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	0.430	0.500
A1	0.000	0.050
b	0.170	0.270
b1	0.270	0.370
c	0.080	0.150
D	1.150	1.250
E	1.150	1.250
E1	0.750	0.850
e	0.800TYP.	
θ	7° REF.	